



Dynasolve 190



Urethane and Silicone Conformal Coating Removal Solvent



Dynasolve 190 is a formulated solvent that is used in the electronics industry for removing urethane and silicone conformal coatings from printed circuit boards and other components.

CLEANING APPLICATIONS:

Urethane conformal coating removal
Silicone conformal coating removal

ADVANTAGES:

More efficient than acetone, MEK & other solvents
Formulated to be highly selective
Available in gel form for spot removal
Ability to use at room temperature

SPECIFICATIONS:

Specific gravity:	0.84
Boiling point:	149°F (65°C)
Flash point:	53°F (12°C)

MATERIALS REMOVED:

Urethane and silicone conformal coatings

PRODUCT USAGE GUIDELINES

(SEE SDS FOR EH&S INFORMATION)

1. Immerse board or device in Dynasolve 190 at room temperature.
2. Observe carefully. Once conformal coating has been removed, it is critical to rinse with alcohol prior to rinsing with water.
3. For partial/spot removal, apply locally with appropriate application tools.
 - Dynasolve 190 is also available in a thick, gelatinous form for spot removal.

MATERIAL COMPATIBILITY:

Recommended materials including:

Most metals
Teflon®
Polyethylene and polypropylene
Neoprene, butyl rubber, polysulfide rubbers
Kynar
Phenolic

Avoid materials including:

Aluminum
Titanium
PVC
Anhydride-cured epoxy coatings



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325-17-077-GLOBAL



1-800-375-0605
Option 8 for 24/7 Service



6550 Oley Speaks Way
Canal Winchester, OH 43110



www.RudolphBros.Com
RBCsupport@RudBro.Com